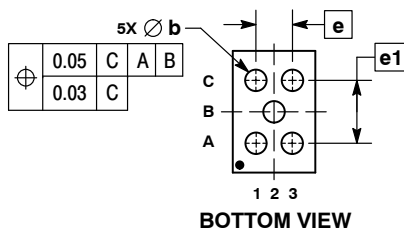
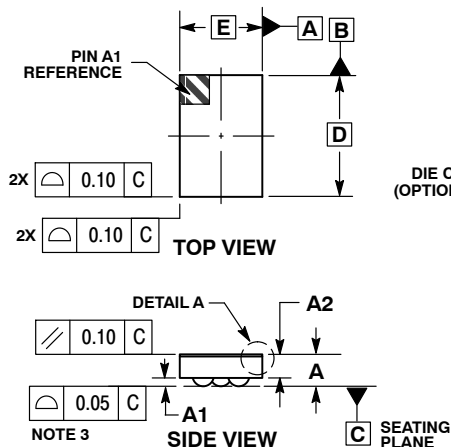




SCALE 4:1

**WLCSP5, 1.34x0.91**  
**CASE 567JQ**  
**ISSUE A**

DATE 09 JUN 2015


**NOTES:**

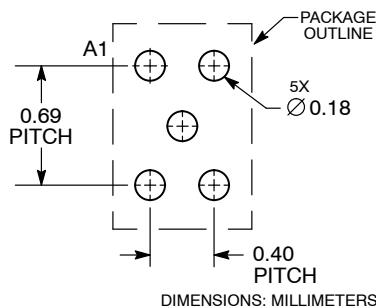
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
4. DIMENSION b IS MEASURED AT THE MAXIMUM BALL DIAMETER PARALLEL TO DATUM C.

MILLIMETERS		
DIM	MIN	MAX
A	---	0.35
A1	0.08	0.12
A2	0.23	REF
A3	0.025	REF
b	0.16	0.20
D	1.34	BSC
E	0.91	BSC
e	0.40	BSC
e1	0.693	BSC

**GENERIC MARKING DIAGRAM\***


X = Specific Device Code  
Y = Year  
W = Work Week

\*This information is generic. Please refer to device data sheet for actual part marking.  
Pb-Free indicator, "G" or microdot "▪", may or may not be present.

**RECOMMENDED SOLDERING FOOTPRINT\***


\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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<b>DESCRIPTION:</b>	<b>WLCSP5, 1.34X0.91</b>	<b>PAGE 1 OF 1</b>

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